|  |  |  |  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| **Manufacturer:** | | | | | **Date:** 16/04/2014 | | | | |
| **BoardSpecifications** | | | | | | | | | |
| **File name** | | CIAA-NXP v1 | | | | **Material** | | | FR4 |
| **Layernumber** | | | 4 |
| **Quantity** | |  | | | | **Thickness** | | | 1.684mm |
| **Size** | | 136.4 x 84.2 mm | | | | **Finish** | | | HAL(Lead Free) |
| **Soldermask** | | Black | | | | **Silkscreen** | | | White |
| **Copperthickness** | | **OuterLayer** | | | | 1 oz | | | |
| **InnerLayer** | | | | 1 oz | | | |
|  | | | | | | | | | |
| **Stack Up** | | | | | | | | | |
| **Layer** | | | **Description** | **Thickness** | | | | **File name** | |
| **Number** | **Name** | | **[oz/mil]** | | | **[mm]** |
| 1 | Top | | Signal | 1 oz | | | 0.035 mm | ciaa-nxp-F\_Cu.gtl | |
|  |  | | Dielectric | 10.7 mil | | | 0.272 mm |  | |
| 2 | InternalPlane1 | | Signal | 1 oz | | | 0.035 mm | ciaa-nxp-Inner1\_Cu.gbr | |
|  |  | | Dielectric | 39.3mil | | | 1 mm |  | |
| 3 | InternalPlane2 | | signal | 1 oz | | | 0.035 mm | Iciaa-nxp-Inner2\_Cu.gbr | |
|  |  | | Dielectric | 10.7 mil | | | 0.272 mm |  | |
| 4 | Bottom | | Signal | 1 oz | | | 0.035 mm | ciaa-nxp-B\_Cu.gbl | |
| **Total boardthickness** | | | | | | | 1.684 mm |  | |

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| --- | --- |
| **Files gerber** | |
| **File name** | **Description** |
| ciaa-nxp-F\_Cu.gtl | Top signal layer |
| ciaa-nxp-Inner1\_Cu.gbr | Plane GND and signal |
| ciaa-nxp-Inner2\_Cu.gbr | PlaneVcc and signal |
| ciaa-nxp-B\_Cu.gbl | Bottom signal layer |
| ciaa-nxp-F\_SilkS.gto | Top silkscreen |
| ciaa-nxp-B\_SilkS.gbo | Bottom silkscreen |
| ciaa-nxp-F\_Mask.gts | Top solder Mask |
| ciaa-nxp-B\_Mask.gbs | Bottom solderMask |
| ciaa-nxp-F\_Paste.gtp | Top solder Past |
| ciaa-nxp-B\_Paste.gbp | Bottom solder Past |
| ciaa-nxp.drl | drill |
| ciaa-nxp-Edge\_Cuts.gbr | Board oultine |